

3685 U.S. PTO  
09/761730



Class	Subclass

**2003-1310**

U.S. UTILITY Patent Application

PATENT NUMBER

O.I.P.E.	PATENT DATE
<i>KW</i> SCANNED <i>AGI</i> Q.A. <i>TM</i>	

APPLICATION NO. 09/761738	CONT/PRIOR D F	CLASS <i>118</i>	SUBCLASS <i>514</i>	ART UNIT <i>1763</i> <i>2824</i>	EXAMINER <i>Lebentritt</i>
------------------------------	-------------------	---------------------	------------------------	--	-------------------------------

APPLICANTS

Shigenobu Maeda

TITLE

Manufacturing method of semiconductor wafer, semiconductor manufacturing apparatus, and semiconductor device

**BEST AVAILABLE COPY**

PTO-2040  
12/99

**ISSUING CLASSIFICATION**

ORIGINAL		CROSS REFERENCE(S)					
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION							

☐ Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> <b>TERMINAL DISCLOSURE</b>  <input type="checkbox"/> The term of this patent subsequent to the date of the last such disclosure has been disclosed.  <input type="checkbox"/> The term of this patent shall not extend beyond the term of the corresponding foreign patent.  <input type="checkbox"/> The term of this patent shall not extend beyond the term of the corresponding foreign patent.	<b>DRAWINGS</b>			<b>CLAIMS ALLOWED</b>	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
	(Assistant Examiner) _____ (Date) _____  (Primary Examiner) _____ (Date) _____  (Legal Instruments Examiner) _____ (Date) _____			<b>NOTICE OF ALLOWANCE MAILED</b>  <b>ISSUE FEE</b> Amount Due _____ Date Paid _____  <b>ISSUE BATCH NUMBER</b>	

**WARNING:**

The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.

Form PTO-436A  
(Rev. 6/99)

FILED WITH: ☐ DISK (CRF) ☐ FICHE ☐ CD-ROM  
(Attached in pocket on right inside flap)

2003-1310